

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	19490	strong near3 bond	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 18:50
2	BRS	4696	weak near3 bond	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 18:51
3	BRS	580	(strong near3 bond) same (weak near3 bond)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 18:51
4	BRS	1951675	semiconduc tor or silicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 18:51
5	BRS	196327	device near3 portion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 18:52
6	BRS	5	((strong near3 bond) same (weak near3 bond)) same (semicondu ctor or silicon)) and (device near3 portion)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 18:52
7	BRS	56	((strong near3 bond) same (weak near3 bond)) same (semicondu ctor or silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 19:05

	Type	Hits	Search Text	DBs	Time Stamp
8	BRS	1337325	bond or bonded or bonding	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 19:05
9	BRS	78624	(semiconductor or silicon) near4 (bond or bonded or bonding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 19:07
10	BRS	54	((strong near3 bond) same (weak near3 bond)) and ((semiconductor or silicon) near4 (bond or bonded or bonding))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 19:07
11	BRS	25	((((strong near3 bond) same (weak near3 bond)) and ((semiconductor or silicon) near4 (bond or bonded or bonding))) not (((strong near3 bond) same (weak near3 bond)) same (semiconductor or silicon)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 19:12

	Type	Hits	Search Text	DBs	Time Stamp
12	BRS	580	((strong near3 bond) same (weak near3 bond)) and (bond or bonded or bonding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 19:12
13	BRS	157534	438/\$.ccls .	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 19:13
14	BRS	12122164	257/\$.ccls .c	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 19:13
15	BRS	287303	257/\$.ccls .	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 19:14
16	BRS	485	((((strong near3 bond) same (weak near3 bond)) and (bond or bonded or bonding)) and (438/\$.ccl s. or 257/\$.ccls .c)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 19:34
17	BRS	1354	438/455	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 19:35

	Type	Hits	Search Text	DBs	Time Stamp
18	BRS	5	(((((strong near3 bond) same (weak near3 bond)) and (bond or bonded or bonding)) and (438/\$.ccl s. or 257/\$.ccls .c)) and 438/455	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 19:39
19	BRS	940	438/458	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 19:40
20	BRS	1124	438/459	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 19:40
21	BRS	3	(((((strong near3 bond) same (weak near3 bond)) and (bond or bonded or bonding)) and (438/\$.ccl s. or 257/\$.ccls .c)) and (438/458 or 438/459)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 19:41
22	BRS	2482	438/455 or 438/458 or 438/459	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/14 19:42
23	BRS	162	selective\$ near4 wafer near4 bond\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 10:10

	Type	Hits	Search Text	DBs	Time Stamp
24	BRS	157534	438/\$.ccls .	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 10:42
25	BRS	287303	257/\$.ccls .	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 10:48
26	BRS	116	(selectiv e\$ near4 wafer near4 bond\$) and (438/\$.ccl s. or 257/\$.ccls .)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 10:49
27	BRS	36202	MEMS	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 10:49
28	BRS	14	((selective \$ near4 wafer near4 bond\$) and (438/\$.ccl s. or 257/\$.ccls .)) and MEMS	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 10:49